



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSZ013NE2LS5I	Issued	26. June 2021
MA#	MA005582135		
Package	PG-TSDSON-8-36	Weight*	35.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.692	1.94	1.94	19379	19379
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		410	
	non noble metal	iron	7439-89-6	0.293	0.82		8209	
	non noble metal	copper	7440-50-8	11.903	33.33	34.20	333337	342059
wire	non noble metal	copper	7440-50-8	0.013	0.04	0.04	363	363
encapsulation	organic material	carbon black	1333-86-4	0.034	0.10		965	
	plastics	epoxy resin	-	1.585	4.44		44384	
	inorganic material	silicondioxide	60676-86-0	15.608	43.71	48.25	437088	482437
leadfinish	non noble metal	tin	7440-31-5	0.420	1.18	1.18	11774	11774
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	88	88
solder	noble metal	silver	7440-22-4	0.024	0.07		661	
	non noble metal	tin	7440-31-5	0.047	0.13		1323	
	non noble metal	lead	7439-92-1	0.874	2.45	2.65	24476	26460
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		141	
	non noble metal	iron	7439-89-6	0.101	0.28		2819	
	non noble metal	copper	7440-50-8	4.087	11.44	11.73	114445	117440
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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